12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260630001.1	PCN Issued	June 30, 2026
Qualification of RFAB as an additional Fab site and TI Clark as additional Assembly site option for select devices		Sample request deadline:	August 29, 2026
		Estimated 1st ship date:	September 28, 2026

Change type(s)
Assembly Site
Assembly Process
Assembly Material
Packing/Shipping/Labeling
Wafer Fab Site
Wafer Fab Material

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site and TI Clark as additional Assembly site option for the devices listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
FFAB	LBC7	200mm	RFAB	LBC7	300mm

Construction Differences are as follows:

	Current	Additional
Assembly site	UTL1	Clark
Wire diam/type	1.3mil Au	1.3mil Cu
Mount compound	SID#PZ0037	4207123
Mold compound	SID#CZ0141	4222198
Lead finish	NiPdAuAg	NiPdAu

Qual details are provided in the Qual Data Section.

Reason for Change:	Supply Continuity
Anticipated impact on Form, Fit, Function, Quality or Reliability:	Physical aspects of the device have changed. Review the Standard Data Packet for more details on the changes
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there

	are no changes to the associated environmental ratings. **RoHS**: ☒ No Change **REACH**: ☒ No Change **Green Status**: ☒ No Change **IEC 62474**: ☒ No Change
Changes to product identification resulting from this PCN:	**Fab Site Information** Chip Site: FFAB; Chip Site Origin Code (20L): TID; Chip Site Country Code (21L): DEU; Chip Site City: Freising **Chip Site: RFAB; Chip Site Origin Code (20L): RFB; Chip Site Country Code (21L): USA; Chip Site City: Richardson** **Assembly Site Information** Assembly Site: UTL1; Assembly Site Origin (22L): NSE; Assembly Country Code (23L): THA; Assembly City: Bangkok Assembly Site: CLARK; Assembly Site Origin (22L): QAB; Assembly Country Code (23L): PHL; Assembly City: Angeles City Sample product shipping label (not actual product label): 
Products Affected:	
TPS61252DSGR	

Qualification Report

Approve Date 12-MAY -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TLV7021DPWR-S	Qual Device: TLV7011DPWR-S	Qual Device: TLV7011DCKR-S	Qual Device: TLV7031DPWR-S	QBS Reference: TPS650810ZWVR
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	-	-	3/231/0
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	-	-	-	-	3/231/0
TC	A4	Temperature Cycle	-40C/85C	1000 Cycles	-	-	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	3/231/0
ELFR	B2	ELFR	125C	48 Hours	-	-	-	-	3/3000/0
ESD	E2	ESD CDM	-	250 Volts	-	-	-	-	2/6/0
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	2/6/0
LU	E4	LU	Per JESD78	-	-	-	-	-	3/18/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	-	1/30/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device TLV7021DPWR-S is qualified at MSL1 260C
Qual Device TLV7011DPWR-S is qualified at NOT CLASSIFIED NOT CLASSIFIED
Qual Device TLV7011DCKR-S is qualified at MSL2 260C
Qual Device TLV7031DPWR-S is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2403-097

Qualification Report

Approve Date 14-October -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS61252DSGR-R	Pcakage QBS Reference: SN27614DSGR	Process QBS Reference: SN65709BA01YFFR	Package QBS Reference: LM27761DSGR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	1/77/0	1/77/0	3/231/0	1/77/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	1/77/0	-	1/77/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	-	3/231/0	-
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	1/77/0	-	-	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	1/77/0	-	3/231/0	1/77/0
HTOL	B1	Life Test	125C	1000 Hours	1/77/0	-	-	1/77/0
HTOL	B1	Life Test	140C	480 Hours	-	-	3/231/8[1]	-
ELFR	B2	ELFR	125C	48 Hours	-	-	1/1000/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	3/66/0	3/15/0
PD	C4	Physical Dimensions	(per mechanical drawing)	-	3/60/0	-	3/15/0	-
ESD	E2	ESD CDM	-	250 Volts	2/6/0	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	2/6/0	-	-	-
LU	E4	LU	Per JESD78	-	3/9/0	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	1/30/0	-

QBS: Qual By Similarity, also known as Generic Data
Qual Device TPS61252DSGR-R is qualified at MSL2 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-NPD-2412-102
[1]-Issue is related to the HTOL oven used. please see the attached 4C and Oven BIB maps.

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

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